

ABSTRACT

An interconnect for attaching a module such as a PCB or a multi-chip module to a circuit substrate comprises a member elongated in a longitudinal direction. The member has at least a first elongated side and a second opposed and generally parallel elongated side. The first and second sides extend in the longitudinal direction. Each of the first and second sides have at least one portion formed by a series of depressions in the respective first and second sides. The depressions extend inwardly from a first outer surface of the first side and a second outer surface of the second side. The depressions are metallized to form leads. A circuit assembly is also provided comprising a multi-chip module having a plurality of electronic elements; a circuit substrate supporting thereon a conductive circuit pattern adapted for connection to the multi-chip module and at least one the interconnects for attaching the multi-chip module to the circuit pattern on the circuit substrate. A process for making the interconnect and a process for assembling the circuit assembly is also provided.